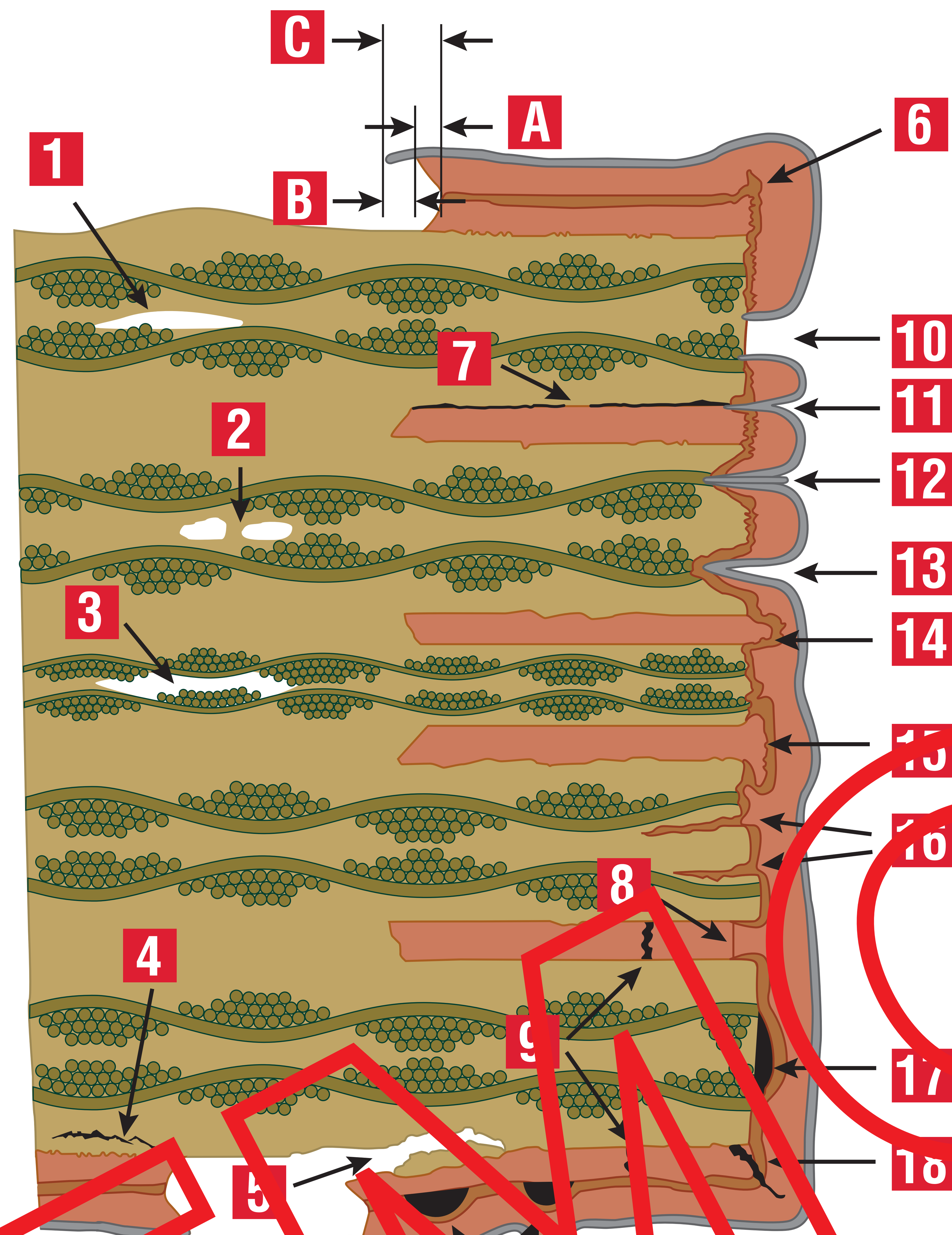
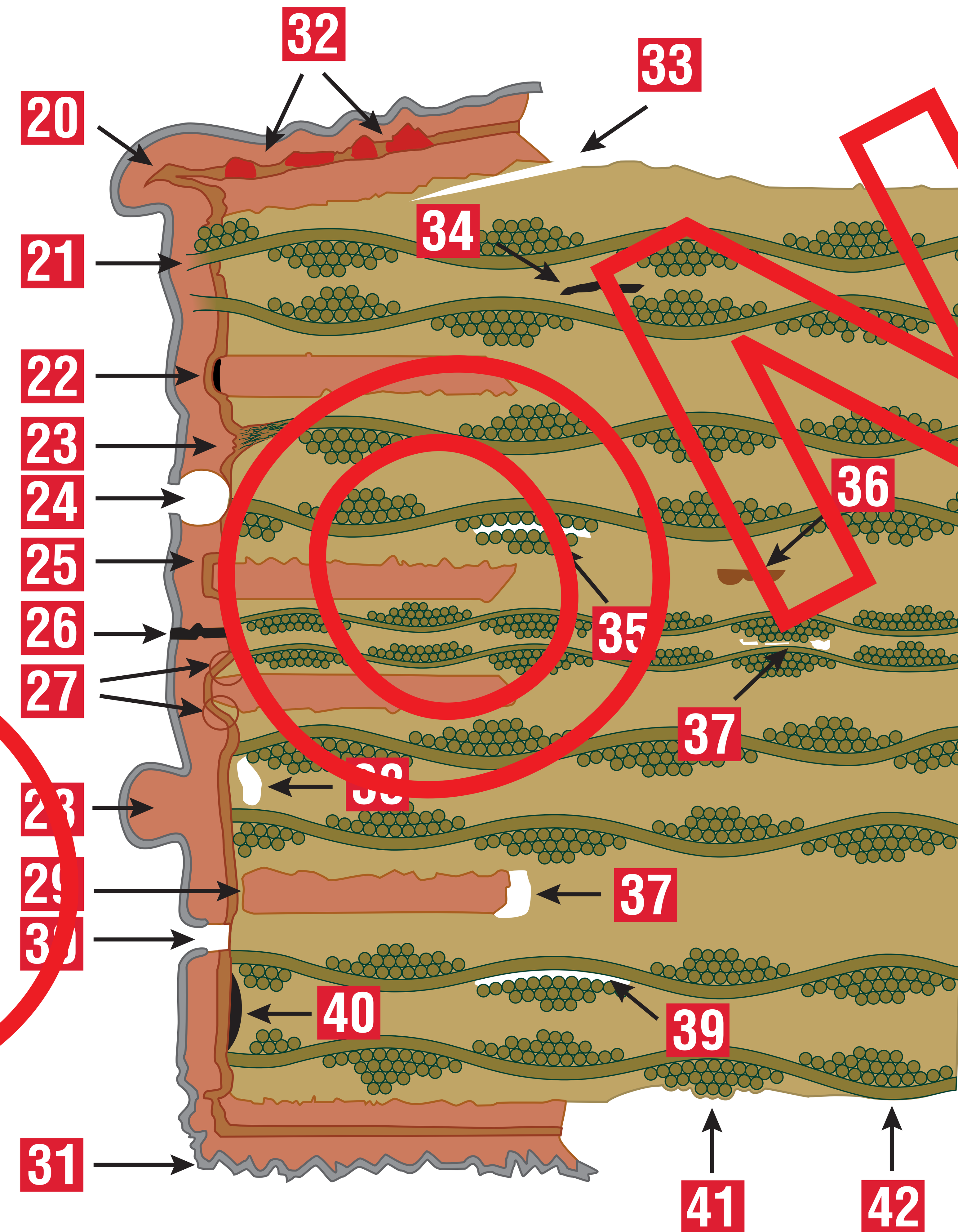
Phenomena in Cross Section of Plated Through Holes





A Undercut
B Outgrowth
C Overhang

1 (Resin) Blistering
2 Laminate Void
3 (Resin) Delamination
4 Pad Cratering
5 Lifted Land Crack
6 Burr
7 Bond Enhancement removed — "Pink Ring"
8 Negative Etchback
9 Foil Crack
10 Hole Plating Void
11 Wedge Void
12 Glass Fiber Void
13 Glass Bundle Void
14 Severe Etchback
15 Nail Heading
16 Drill Wall Tear/Wicking
17 Hole Wall Pull Away
18 Corner Crack
19 (Copper) Blistering

20 Burr Pushed Into Hole
21 Glass Fiber Protrusion
22 Innerlayer (Post) Separation
23 Wicking
24 Over Plating Resist Void
25 (Positive) Etchback
26 Barrel Crack
27 Shadowing
28 Nodule
29 Resin Smear
30 Copper & Over Plate Void
31 Burned Plating
32 Copper Foil Contamination
33 Lifted Land
34 Resin Crack Delamination
35 Crazing
36 Foreign Inclusion
37 Prepreg Void
38 Copper Clad Laminate Void
39 Measling
40 Resin Recession
41 Glass-Weave Texture
42 Glass-Weave Exposure

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Updated to Industry Standard Terminology

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